

Patent claims

1. A polymer mixture containing
5 - one or more semiconductive polymers,
 - one or more non-semiconductive polymers.
2. The polymer mixture as claimed in claim 1,
characterized in that the semiconductive
10 polymer/the semiconductive polymers is/are
polythiophene, polyfluorene and/or
polythienylenevinylene.
3. The polymer mixture as claimed in either of the
15 preceding claims, characterized in that the non-
semiconductive polymer/the non-semiconductive
polymers is/are polystyrene, polymethyl
methacrylate, cymel and/or polyisobutyl.
- 20 4. The polymer mixture as claimed in any of the
preceding claims, characterized in that it
contains solvents, in particular chloroform,
toluene, ketones, dioxane and/or heptane.
- 25 5. The polymer mixture as claimed in any of the
preceding claims, characterized in that it
contains molecules smaller than polymers, in
particular oligomers, conductive molecules and/or
semiconductive molecules.
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6. The polymer mixture as claimed in any of the
preceding claims, characterized in that it
consists of said substances and customary
additives.
- 35 7. The polymer mixture as claimed in any of the
preceding claims, characterized in that it has a
viscosity of more than 8 mPa.s, in particular more
than 80 mPa.s.

8. A printing process, in particular screen printing, flexographic printing, offset printing, gravure printing and/or pad printing process, in which a polymer mixture as claimed in any of the preceding claims is used.
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9. A double layer containing
 - one or more semiconductive polymers in one of its layers,
 - one or more non-semiconductive polymers in its other layer.10
10. A process for the production of a double layer as claimed in claim 9, in which a polymer mixture as claimed in any of claims 1 to 7 is used.
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11. An electronic component, in particular circuit, which is produced using a polymer mixture as claimed in any of claims 1 to 7 and/or has a double layer as claimed in claim 9.
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